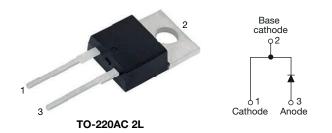
Vishay Semiconductors

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Hyperfast Rectifier, 15 A FRED Pt[®]



PRIMARY CHARACTERISTICS						
I _{F(AV)}	15 A					
V _R	600 V					
V _F at I _F	1.55 V					
t _{rr} (typ.)	18 ns					
T _J max.	175 °C					
Package	TO-220AC 2L					
Circuit configuration	Single					

FEATURES

- Hyperfast recovery time, extremely low Q_{rr}
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC[®]-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Peak repetitive reverse voltage	V _{RRM}		600	V			
Average rectified forward current in DC	I _{F(AV)}	T _C = 141 °C	15	٨			
Non-repetitive peak surge current	I _{FSM}	$T_J = 25 \ ^{\circ}C$	120	A			
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS MIN. TYP. MA					
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-		
Forward voltage	V _F	I _F = 15 A	-	2.5	3.4	4 V	
		I _F = 15 A, T _J = 150 °C	-	1.55	2		
		$V_{R} = V_{R}$ rated	-	0.02	36		
Reverse leakage current I _R		$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	40	250	μA	
Junction capacitance	CT	V _R = 600 V	-	12	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH	



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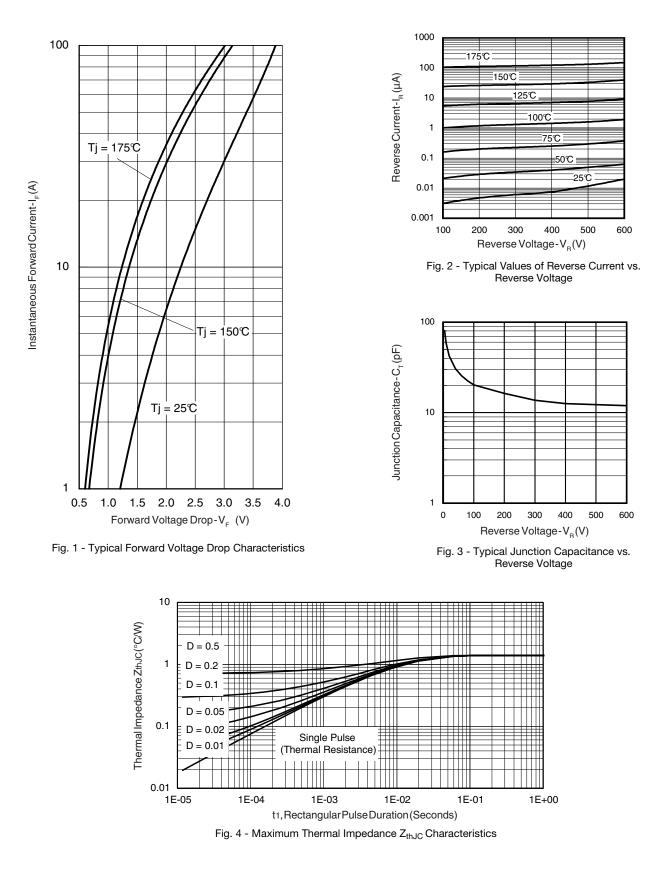
DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 \text{ A}, \ dI_F/dt = 100$	$I_F = 1 \text{ A}, \text{ d}I_F/\text{d}t = 100 \text{ A}/\mu\text{s}, \text{ V}_R = 30 \text{ V}$		17	23	-	
Reverse recovery time	+	I _F = 15 A, dI _F /dt = 10	I _F = 15 A, dI _F /dt = 100 A/µs, V _R = 30 V		18	30		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	20	-	ns	
		T _J = 125 °C	I _F = 15 A, dI _F /dt = 200 A/μs, V _R = 390 V	-	45	-		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	2.7	-	A	
Feak recovery current		T _J = 125 °C		-	5.5	-		
	0	T _J = 25 °C		-	26	-	nC	
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	130	-		
Reverse recovery time	t _{rr}		In = 15 A	-	32	-	ns	
Peak recovery current	I _{RRM}		dl _F /dt = 800 A/µs,	-	17	-	Α	
Reverse recovery charge	Q _{rr}		V _R = 390 V	-	290	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C		
Thermal resistance,	Б		-	1.2	1.4			
junction-to-case	R _{thJC}		-	3.7	4.3	Ĩ		
Thermal resistance, junction to ambient	R _{thJA}	R _{thJA} Typical socket mount		-	70	°C/W		
Typical thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	-		
Weight			-	2	-	g		
Weight			-	0.07	-	oz.		
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-220AC 2L	ETX1506					



VS-ETX1506-M3

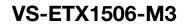
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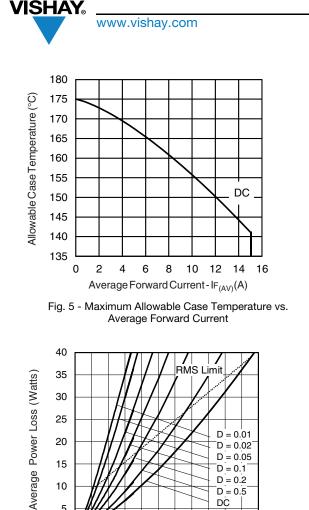
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Average Forward Current- $IF_{(AV)}(A)$ Fig. 6 - Forward Power Loss Characteristics

6 8 10 12 14 16 18 20 22

20

15

10

5

0

0 2 4 D = 0.01

D = 0.02 D = 0.05

D = 0.1

D = 0.2

D = 0.5 DĊ

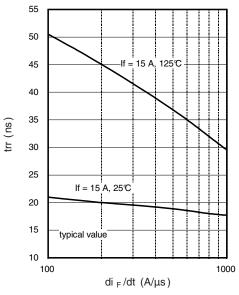


Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

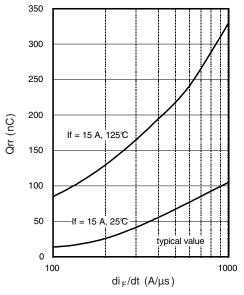


Fig. 8 - Typical Stored Charge vs. dl_F/dt

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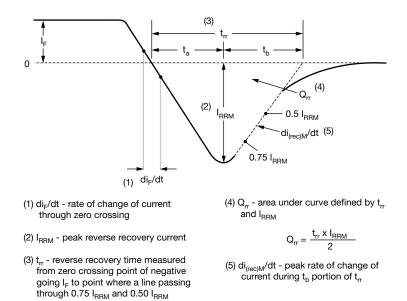
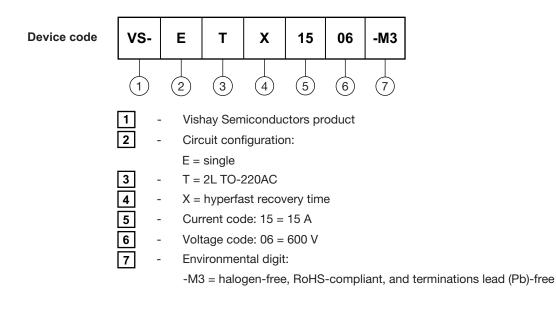


Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

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extrapolated to zero current.

ORDERING INFORMATION (Example)								
PREFERRED P/N	PREFERRED P/N BASE QUANTITY PACKAGING DESCRIPTION							
VS-ETX1506-M3	50	Antistatic plastic tubes						

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96156				
Part marking information	www.vishay.com/doc?95391				

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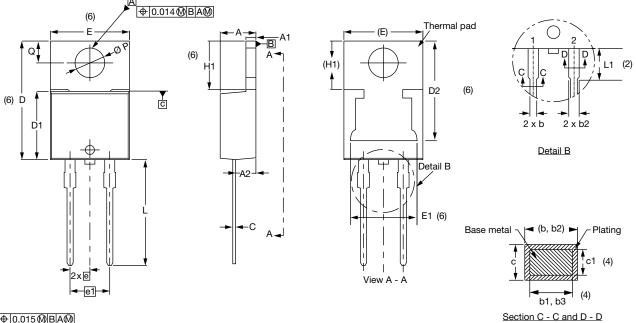
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TO-220AC 2L

DIMENSIONS in millimeters and inches



⊕0.015@BA@



SYMBOL	MILLIN	IETERS INCHES		NOTES	
STWDOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.50	2.92	0.098	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.35	0.585	0.604	3
D1	8.38	9.02	0.330	0.355	

SYMBOL	MILLIN	IETERS	INCHES		NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	11.68	13.30	0.460	0.524	6, 7
Е	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
e	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØР	3.54	3.91	0.139	0.154	
Q	2.60	3.00	0.102	0.118	

Conforms to JEDEC[®] outline TO-220AC

Notes

⁽²⁾ Lead dimension and finish uncontrolled in L1

(4) Dimension b1, b3, and c1 apply to base metal only

- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- ⁽⁷⁾ Outline conforms to JEDEC[®] TO-220, except D2

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 $^{^{(1)}\,}$ Dimensioning and tolerancing as per ASME Y14.5M-1994 $\,$

⁽³⁾ Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁵⁾ Controlling dimensions: inches



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